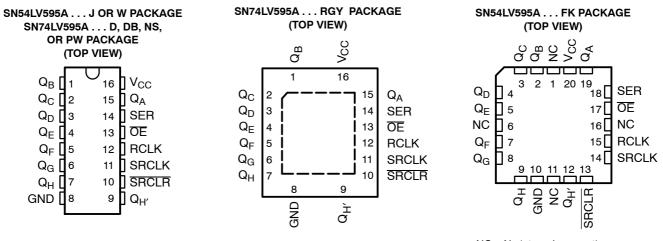
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- 2-V to 5.5-V V_{CC} Operation
- Max t_{pd} of 7.1 ns at 5 V
- Typical V_{OLP} (Output Ground Bounce) <0.8 V at V_{CC} = 3.3 V, T_A = 25° C
- Typical V_{OHV} (Output V_{OH} Undershoot) >2.3 V at V_{CC} = 3.3 V, T_A = 25°C
- Support Mixed-Mode Voltage Operation on **All Ports**
- 8-Bit Serial-In, Parallel-Out Shift

- Ioff Supports Partial-Power-Down Mode Operation
- Shift Register Has Direct Clear
- Latch-Up Performance Exceeds 250 mA Per **JESD 17**
- ESD Protection Exceeds JESD 22 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)



NC - No internal connection

description/ordering information

The 'LV595A devices are 8-bit shift registers designed for 2-V to 5.5-V V_{CC} operation.

T _A	PACK	AGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	QFN – RGY	Reel of 1000	SN74LV595ARGYR	LV595A
		Tube of 40	SN74LV595ADG3	11/5054
40%C to 95%C	SOIC – D	Reel of 2500	SN74LV595ADR	LV595A
	SOP – NS	Reel of 2000	SN74LV595ANSR	74LV595A
–40°C to 85°C	SSOP – DB	Reel of 2000	SN74LV595ADBR	LV595A
		Tube of 90	SN74LV595APW	
	TSSOP – PW	Reel of 2000	SN74LV595APWRG3	LV595A
		Reel of 250	SN74LV595APWT	
	CDIP – J	Tube of 25	SNJ54LV595AJ	SNJ54LV595AJ
–55°C to 125°C	CFP – W	Tube of 150	SNJ54LV595AW	SNJ54LV595AW
	LCCC – FK	Tube of 55	SNJ54LV595AFK	SNJ54LV595AFK

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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description/ordering information (continued)

These devices contain an 8-bit serial-in, parallel-out shift register that feeds an 8-bit D-type storage register. The storage register has parallel 3-state outputs. Separate clocks are provided for both the shift and storage register. The shift register has a direct overriding clear (SRCLR) input, serial (SER) input, and a serial output for cascading. When the output-enable (OE) input is high, all outputs except Q_{H'} are in the high-impedance state.

Both the shift register clock (SRCLK) and storage register clock (RCLK) are positive-edge triggered. If both clocks are connected together, the shift register always is one clock pulse ahead of the storage register.

To ensure the high-impedance state during power up or power down, OE should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

These devices are fully specified for partial-power-down applications using loff. The loff circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

		INPUTS			FUNCTION
SER	SRCLK	SRCLR	RCLK	ŌĒ	FUNCTION
Х	Х	Х	Х	Н	Outputs Q _A -Q _H are disabled.
х	Х	Х	Х	L	Outputs Q _A –Q _H are enabled.
х	Х	L	Х	Х	Shift register is cleared.
L	Ŷ	н	х	х	First stage of the shift register goes low. Other stages store the data of previous stage, respectively.
Н	\uparrow	Н	х	х	First stage of the shift register goes high. Other stages store the data of previous stage, respectively.
Х	Х	Х	Ŷ	Х	Shift-register data is stored in the storage register.

FUNCTION TABLE



<u>OE</u> _____ RCLK _____ SRCLK 11 SER _____ 1D 3D Q 15 Q_A > C3 Q > C1 R 2D 3D Q 1 Q_B > C3 Q > C2 R 3D 2D Q 2 Q_C > C3 Q > C2 R 2D 3D Q 3 Q_D > C2 > C3 Q R 2D 3D Q 4 Q_E > C2 > C3 Q R 2D 3D Q 5 Q_F > C2 > C3 Q R 3D 2D Q <u>6</u> Q_G > C2 > C3 Q R 2D 3D Q 7 Q_H > C2 > C3 Q R 9 Q_H

logic diagram (positive logic)

Pin numbers shown are for the D, DB, J, NS, PW, RGY, and W packages.



SN54LV595A, SN74LV595A 8-BIT SHIFT REGISTERS WITH 3-STATE OUTPUT REGISTERS SCLS4140 - APRIL 1998 - REVISED JANUARY 2011

timing diagram

SRCLK	
SER	
RCLK	
SRCLR	
ŌĒ	
Q _A	
Q _B	
Q _C	
QD	
Q _E	
Q _F	
Q _G	
Q _H	
Q _{H′}	

NOTE: XXXX implies that the output is in 3-State mode.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}
$ \begin{array}{llllllllllllllllllllllllllllllllllll$
(see Note 3): NS package
(see Note 4): RGY package

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

2. This value is limited to 5.5 V maximum.

3. The package thermal impedance is calculated in accordance with JESD 51-7.

4. The package thermal impedance is calculated in accordance with JESD 51-5.



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recommended operating conditions (see Note 5)

			SN54L	V595A	SN74L	V595A		
			MIN	MAX	MIN	MAX	UNIT	
V _{CC}	Supply voltage		2	5.5	2	5.5	V	
		V _{CC} = 2 V	1.5		1.5			
.,		V_{CC} = 2.3 V to 2.7 V	$V_{CC} imes 0.7$		$V_{CC} imes 0.7$.,	
V _{IH}	High-level input voltage	V_{CC} = 3 V to 3.6 V	$V_{CC} imes 0.7$		$V_{CC} imes 0.7$		V	
		V_{CC} = 4.5 V to 5.5 V	$V_{CC} imes 0.7$		$V_{CC} imes 0.7$			
		V _{CC} = 2 V		0.5		0.5		
.,		V_{CC} = 2.3 V to 2.7 V		$V_{CC} imes 0.3$		$V_{CC} imes 0.3$		
V _{IL}	Low-level input voltage	V_{CC} = 3 V to 3.6 V		$V_{CC}\!\times\!0.3$		$V_{CC}\!\times\!0.3$	V	
		V_{CC} = 4.5 V to 5.5 V		$V_{CC} imes 0.3$		$V_{CC}\!\times\!0.3$		
VI	Input voltage		0	5.5	0	5.5	V	
	<u> </u>	High or low state	0	V _{CC}	0	V _{CC}		
Vo	Output voltage	3-state	0	5.5	0	5.5	V	
		$V_{CC} = 2 V$	vo	-50		-50	μA	
		V_{CC} = 2.3 V to 2.7 V	20	-2		-2		
I _{OH}	High-level output current	V_{CC} = 3 V to 3.6 V	Q	-8		-8	mA	
		V_{CC} = 4.5 V to 5.5 V		-16		-16		
		V _{CC} = 2 V		50		50	μA	
		V_{CC} = 2.3 V to 2.7 V		2		2		
I _{OL}	Low-level output current	V_{CC} = 3 V to 3.6 V		8		8	mA	
		V_{CC} = 4.5 V to 5.5 V		16		16		
		V_{CC} = 2.3 V to 2.7 V		200		200		
Δt/Δv	Input transition rise or fall rate	V_{CC} = 3 V to 3.6 V		100		100	ns/V	
		V_{CC} = 4.5 V to 5.5 V		20		20		
Τ _Α	Operating free-air temperature		-55	125	-40	85	°C	

NOTE 5: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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DAD		TEAT CONDITIONS		SN54	4LV595A	SN7	4LV595A	
PAH	AMETER	TEST CONDITIONS	V _{cc}	MIN	TYP MAX	MIN	TYP MAX	UNIT
		I _{OH} = -50 μA	2 V to 5.5 V	V _{CC} -0.1		V _{CC} -0.1		
		I _{OH} = -2 mA	2.3 V	2		2		
	Q _{H′}	I _{OH} = -6 mA	0.14	2.48		2.48		
V _{OH}	$Q_A - Q_H$	I _{OH} = -8 mA	3 V	2.48		2.48		V
	Q _{H′}	I _{OH} = -12 mA	(=) (3.8		3.8		
	$Q_A - Q_H$	I _{OH} = -16 mA	4.5 V	3.8		3.8		
		I _{OL} = 50 μA	2 V to 5.5 V		0.1		0.1	
		I _{OL} = 2 mA	2.3 V		0.4		0.4	
v	Q _{H′}	I _{OL} = 6 mA	0.1/	ک 0.44			0.44	v
V _{OL}	$Q_{A}-Q_{H}$	I _{OL} = 8 mA	3 V		<u>ن</u> 0.44		0.44	v
	Q _{H′}	I _{OL} = 12 mA	4.5.14	10	0.55		0.55	
	$Q_A - Q_H$	I _{OL} = 16 mA	4.5 V	A.	0.55		0.55	
l _l		$V_{I} = 5.5 V \text{ or GND}$	0 to 5.5 V		±1		±1	μA
I _{OZ}		$V_{O} = V_{CC}$ or GND, $Q_{A}-Q_{H}$	1 5.5 V		±5		±5	μA
I _{CC}		$V_{I} = V_{CC} \text{ or } GND, \qquad I_{O} = 0$	5.5 V		20		20	μA
I _{off}		$V_{I} \text{ or } V_{O} = 0 \text{ to } 5.5 \text{ V}$	0		5		5	μA
Ci		V _I = V _{CC} or GND	3.3 V		3.5		3.5	pF

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

timing requirements over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

			T _A = 2	25°C	SN54L	/595A	SN74L	/595A	
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
		SRCLK high or low	7		7.5	À	7.5		
tw	Pulse duration	RCLK high or low	7		7.5	EN	7.5		ns
		SRCLR low			6.5	EL	6.5		
		SER before SRCLK↑	5.5		5.5 🗸	8	5.5		
		SRCLK [↑] before RCLK ^{↑†}	8		9		9		
t _{su}	Setup time	SRCLR low before RCLK1	8.5		9.5		9.5		ns
		SRCLR high (inactive) before SRCLK↑	4		4		4		
t _h	Hold time	SER after SRCLK1	1.5		1.5		1.5		ns

[†] This setup time allows the storage register to receive stable data from the shift register. The clocks can be tied together, in which case the shift register is one clock pulse ahead of the storage register.



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timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

			T _A = 2	25°C	SN54L	/595A	SN74L	/595A	
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
		SRCLK high or low	5.5		5.5		5.5		
tw	Pulse duration	RCLK high or low	5.5		5.5	EW	5.5		ns
		SRCLR low	5		5	EL	5		
		SER before SRCLK1	3.5		3.5 🗸	2	3.5		
Ι.	0.1	SRCLK [↑] before RCLK ^{↑†}	8		8.5		8.5		
t _{su}	t _{su} Setup time	SRCLR low before RCLK [↑]	8		20		9		ns
		SRCLR high (inactive) before SRCLK	3		\$ 3		3		
t _h	Hold time	SER after SRCLK1	1.5		1.5		1.5		ns

[†] This setup time allows the storage register to receive stable data from the shift register. The clocks can be tied together, in which case the shift register is one clock pulse ahead of the storage register.

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

			T _A = 2	25°C	SN54L	V595A	SN74L	/595A	
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
		SRCLK high or low	5		5		5		
tw	Pulse duration	RCLK high or low	5		5	EW	5		ns
		SRCLR low	5.2		5.2	EL	5.2		
		SER before SRCLK↑	3		3 🗸	Q. 2	3		
Ι.		SRCLK [↑] before RCLK ^{↑†}	5		5		5		
t _{su}	t _{su} Setup time	SRCLR low before RCLK1	5		5		5		ns
		SRCLR high (inactive) before SRCLK	2.5		2.5		2.5		
t _h	Hold time	SER after SRCLK↑	2		2		2		ns

[†] This setup time allows the storage register to receive stable data from the shift register. The clocks can be tied together, in which case the shift register is one clock pulse ahead of the storage register.



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	FROM	то	LOAD	T,	₄ = 25°C	;	SN54L	V595A	SN74L	/595A	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			C _L = 15 pF	65*	80*		45*		45		
f _{max}			C _L = 50 pF	60	70		40		40		MHz
t _{PLH}					8.4*	14.2*	1*	15.8*	1	15.8	
t _{PHL}	RCLK	$Q_A - Q_H$			8.4*	14.2*	1*	15.8*	1	15.8	
t _{PLH}		<u> </u>	1		9.4*	19.6*	1*	22.2*	1	22.2	
t _{PHL}	SRCLK	Q _H ′			9.4*	19.6*	1*	22.2*	1	22.2	
t _{PHL}	SRCLR	Q _{H′}	C _L = 15 pF		8.7*	14.6*	1*	16.3*	1	16.3	ns
t _{PZH}	<u></u>		1		8.2*	13.9*	1*	15*	1	15	
t _{PZL}	ŌĒ	$Q_A - Q_H$			10.9*	18.1*	1*	20.3*	1	20.3	
t _{PHZ}			1		8.3*	13.7*	1*	15.6*	1	15.6	

 $C_L = 50 \text{ pF}$

15.2*

17.2

17.2

22.5

22.5

18.8

17

21

18.3

20.9

9.2*

11.2

11.2

13.1

13.1

12.4

10.8

13.4

12.2

14

1¢

 \mathbb{R}^1

1

1

1

1

1

1

1

1

16.7*

19.3

19.3

25.5

25.5

21.1

18.3

23

19.5

22.6

1

1

1

1

1

1

1

1

1

1

16.7

19.3

19.3

25.5

25.5

21.1

18.3

23

19.5

22.6

ns

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

 $Q_A - Q_H$

 $Q_A - Q_H$

Q_H′

Q_{H′}

 $\mathbf{Q}_{\mathsf{A}}-\mathbf{Q}_{\mathsf{H}}$

 $Q_{A}-Q_{H}$

ŌĒ

RCLK

SRCLK

SRCLR

OE

ŌĒ

t_{PLZ}

t_{PLH}

t_{PHL}

t_{PLH}

t_{PHL}

t_{PHL}

t_{PZH}

t_{PZL}

t_{PHZ}

t_{PLZ}

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switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

	FROM	то	LOAD	T,	A = 25°C	;	SN54L	V595A	SN74L	/595A	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			C _L = 15 pF	80*	120*		70*		70		
f _{max}			C _L = 50 pF	55	105		50		50		MHz
t _{PLH}					6*	11.9*	1*	13.5*	1	13.5	
t _{PHL}	RCLK	$Q_{A}-Q_{H}$			6*	11.9*	1*	13.5*	1	13.5	
t _{PLH}					6.6*	13*	1*	15*	1	15	
t _{PHL}	SRCLK	Q _H ′			6.6*	13*	1*	15*	1	15	
t _{PHL}	SRCLR	Q _H ′	C _L = 15 pF		6.2*	12.8*	1*	13.7*	1	13.7	ns
t _{PZH}					6*	11.5*	1*	13.5*	1	13.5	j 2
t _{PZL}	OE	$Q_A - Q_H$			7.8*	11.5*	1*	13.5*	1	13.5	
t _{PHZ}	~=				6.1*	14.7*	1*	15.2*	1	15.2	
t _{PLZ}	ŌĒ	Q _A –Q _H			6.3*	14.7*	s.	15.2*	1	15.2	
t _{PLH}	5011/				7.9	15.4	0 ¹	17	1	17	
t _{PHL}	RCLK	$Q_A - Q_H$			7.9	15.4	Q 1	17	1	17	
t _{PLH}					9.2	16.5	1	18.5	1	18.5	
t _{PHL}	SRCLK	Q _H ′			9.2	16.5	1	18.5	1	18.5	
t _{PHL}	SRCLR	Q _H ′	C _L = 50 pF		9	16.3	1	17.2	1	17.2	ns
t _{PZH}	<u></u>				7.8	15	1	17	1	17	
t _{PZL}	ŌĒ	Q _A –Q _H			9.6	15	1	17	1	17	
t _{PHZ}					8.1	15.7	1	16.2	1	16.2	
t _{PLZ}	ŌE	$Q_A - Q_H$			9.3	15.7	1	16.2	1	16.2	

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

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switching	characteristics	over	recommended	operating	free-air	temperature	range,
$V_{CC} = 5 V \pm$	0.5 V (unless oth	erwise	noted) (see Figu	re 1)		-	-

	FROM	то	LOAD	T,	₄ = 25°C	;	SN54L	V595A	SN74L	√595A	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			C _L = 15 pF	135*	170*		115*		115		
f _{max}			C _L = 50 pF	120	140		95		95		MHz
t _{PLH}	DOLK				4.3*	7.4*	1*	8.5*	1	8.5	
t _{PHL}	RCLK	$Q_A - Q_H$			4.3*	7.4*	1*	8.5*	1	8.5	
t _{PLH}		0			4.5*	8.2*	1*	9.4*	1	9.4	
t _{PHL}	SRCLK	Q _H ′			4.5*	8.2*	1*	9.4*	1	9.4	
t _{PHL}	SRCLR	Q _H ′	C _L = 15 pF		4.5*	8*	1*	9.1*	1	9.1	ns
t _{PZH}	~=		1		4.3*	8.6*	1*	10*	1	10	
t _{PZL}	ŌĒ	$Q_A - Q_H$			5.4*	8.6*	1*	×10*	1	10	
t _{PHZ}					2.4*	6*	1*	7.1*	1	7.1	
t _{PLZ}	ŌĒ	$Q_A - Q_H$			2.7*	5.1*	₹.)	7.2*	1	7.2	
t _{PLH}	RCLK	0.0			5.6	9.4	$\overline{Q_0}$	10.5	1	10.5	
t _{PHL}	ROLK	$Q_A - Q_H$			5.6	9.4	1 40	10.5	1	10.5	
t _{PLH}	SRCLK	0			6.4	10.2	1	11.4	1	11.4	
t _{PHL}	SRULK	Q _H ′			6.4	10.2	1	11.4	1	11.4	
t _{PHL}	SRCLR	Q _H ′	C _L = 50 pF		6.4	10	1	11.1	1	11.1	ns
t _{PZH}		<u> </u>]		5.7	10.6	1	12	1	12	
t _{PZL}	ŌĒ	$Q_A - Q_H$			6.8	10.6	1	12	1	12	
t _{PHZ}	ŌE	0.0]		3.5	10.3	1	11	1	11	
t _{PLZ}	UE	$Q_A - Q_H$			3.4	10.3	1	11	1	11	

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics, V_{CC} = 3.3 V, C_L = 50 pF, T_A = 25 $^{\circ}\text{C}$ (see Note 6)

		SN	iΑ		
	PARAMETER	MIN	TYP	MAX	UNIT
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		0.3		V
V _{OL(V)}	Quiet output, minimum dynamic V _{OL}		-0.2		V
V _{OH(V)}	Quiet output, minimum dynamic V _{OH}		2.8		V
V _{IH(D)}	High-level dynamic input voltage	2.31			V
V _{IL(D)}	Low-level dynamic input voltage			0.99	V

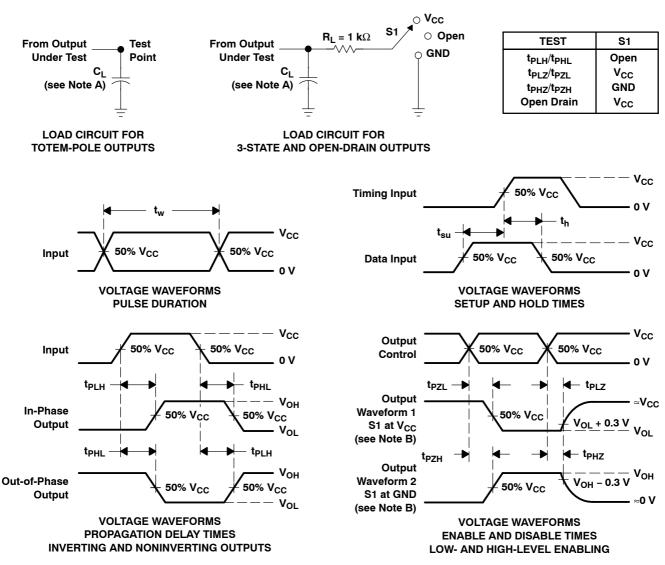
NOTE 6: Characteristics are for surface-mount packages only.

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CO	NDITIONS	V _{CC}	TYP	UNIT
<u> </u>	Dever dissipation conscitutes	С <u>БОр</u> Г	f = 10 MHz	3.3 V	111	pF
Opd	Power dissipation capacitance	C _L = 50 pF,		5 V	114	рг



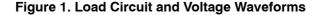
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PARAMETER MEASUREMENT INFORMATION

NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z₀ = 50 Ω , t_f \leq 3 ns, t_f \leq 3 ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{P71} and t_{P7H} are the same as t_{en} .
- G. t_{PHL} and t_{PLH} are the same as t_{pd} .
- H. All parameters and waveforms are not applicable to all devices.







11-Apr-2013

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings (4)	Samples
SN74LV595AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV595A	Samples
SN74LV595ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV595A	Samples
SN74LV595ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV595A	Samples
SN74LV595ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV595A	Samples
SN74LV595ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV595A	Samples
SN74LV595ADRG3	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	LV595A	Samples
SN74LV595ADRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV595A	Samples
SN74LV595ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	74LV595A	Samples
SN74LV595ANSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	74LV595A	Samples
SN74LV595ANSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	74LV595A	Samples
SN74LV595APWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV595A	Samples
SN74LV595APWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV595A	Samples
SN74LV595APWRG3	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	LV595A	Samples
SN74LV595APWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV595A	Samples
SN74LV595APWT	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV595A	Samples
SN74LV595APWTE4	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV595A	Samples
SN74LV595APWTG4	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV595A	Samples



11-Apr-2013

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
SN74LV595ARGYR	ACTIVE	VQFN	RGY	16	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	LV595A	Samples
SN74LV595ARGYRG4	ACTIVE	VQFN	RGY	16	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	LV595A	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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OTHER QUALIFIED VERSIONS OF SN74LV595A :

Automotive: SN74LV595A-Q1



www.ti.com

PACKAGE OPTION ADDENDUM

11-Apr-2013

Enhanced Product: SN74LV595A-EP

NOTE: Qualified Version Definitions:

- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product Supports Defense, Aerospace and Medical Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



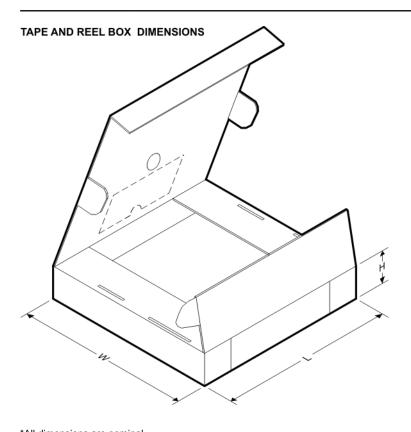
*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV595ADR	SOIC	D	16	2500	330.0	16.8	6.5	10.3	2.1	8.0	16.0	Q1
SN74LV595ADRG3	SOIC	D	16	2500	330.0	16.8	6.5	10.3	2.1	8.0	16.0	Q1
SN74LV595ADRG4	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LV595ANSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LV595APWR	TSSOP	PW	16	2000	330.0	12.4	7.0	5.6	1.6	8.0	12.0	Q1
SN74LV595APWRG3	TSSOP	PW	16	2000	330.0	12.4	7.0	5.6	1.6	8.0	12.0	Q1
SN74LV595APWRG4	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV595APWT	TSSOP	PW	16	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV595ARGYR	VQFN	RGY	16	3000	330.0	12.4	3.8	4.3	1.5	8.0	12.0	Q1

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PACKAGE MATERIALS INFORMATION

5-Oct-2013



*All dimensions are nominal							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV595ADR	SOIC	D	16	2500	364.0	364.0	27.0
SN74LV595ADRG3	SOIC	D	16	2500	364.0	364.0	27.0
SN74LV595ADRG4	SOIC	D	16	2500	333.2	345.9	28.6
SN74LV595ANSR	SO	NS	16	2000	367.0	367.0	38.0
SN74LV595APWR	TSSOP	PW	16	2000	364.0	364.0	27.0
SN74LV595APWRG3	TSSOP	PW	16	2000	364.0	364.0	27.0
SN74LV595APWRG4	TSSOP	PW	16	2000	367.0	367.0	35.0
SN74LV595APWT	TSSOP	PW	16	250	367.0	367.0	35.0
SN74LV595ARGYR	VQFN	RGY	16	3000	367.0	367.0	35.0

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



4211283-4/E 08/12

D (R-PDSO-G16) PLASTIC SMALL OUTLINE Stencil Openings (Note D) Example Board Layout (Note C) –16x0,55 -14x1,27 -14x1,27 16x1,50 5,40 5.40 Example Non Soldermask Defined Pad Example Pad Geometry (See Note C) 0,60 .55 Example 1. Solder Mask Opening (See Note E) -0,07 All Around

NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES:

A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994. β . This drawing is subject to change without notice.

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.

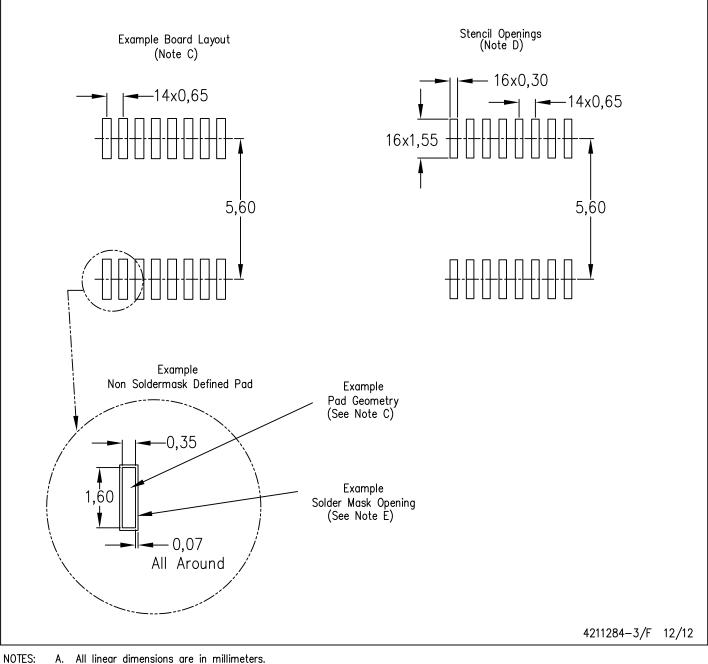
Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

E. Falls within JEDEC MO-153



PW (R-PDSO-G16)

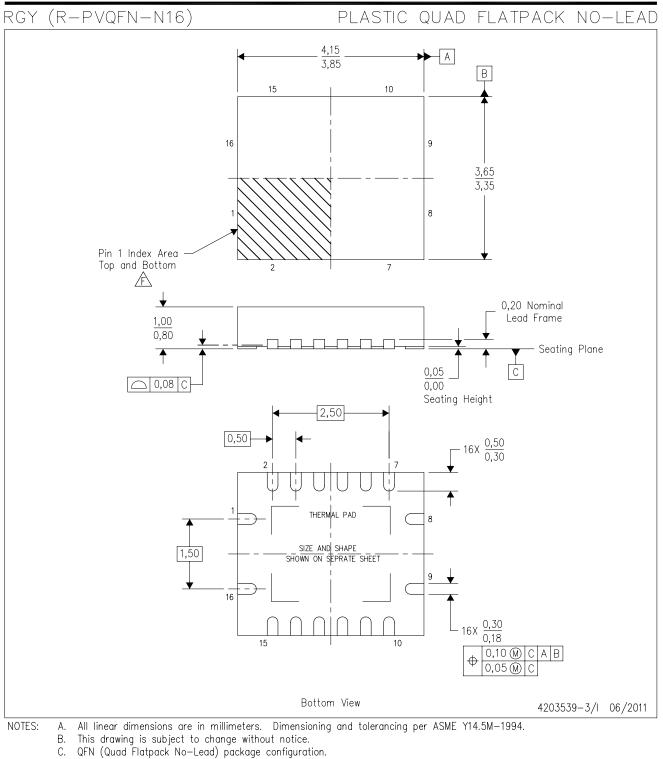
PLASTIC SMALL OUTLINE



- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA



- D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
- Ε. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
- Æ Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated.
- The Pin 1 identifiers are either a molded, marked, or metal feature.
- G. Package complies to JEDEC MO-241 variation BA.



RGY (R-PVQFN-N16)

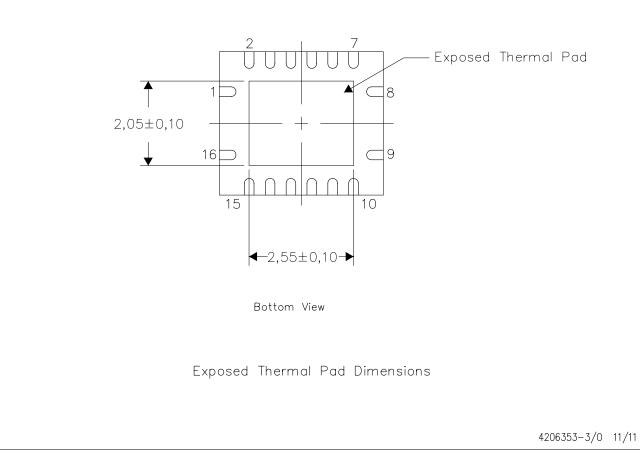
PLASTIC QUAD FLATPACK NO-LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

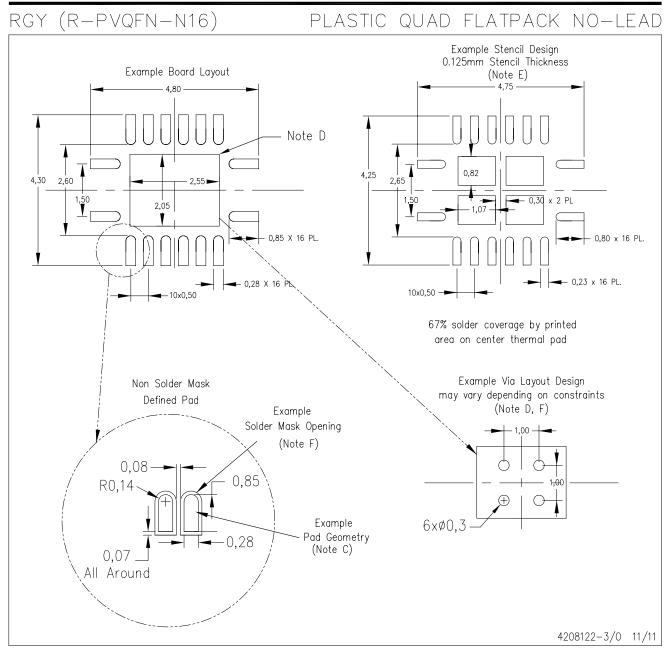
For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



NOTE: All linear dimensions are in millimeters





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.

D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <http://www.ti.com>.

E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.

F. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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